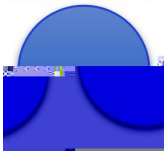




SSL,VsC'6Ue YSò2@ù P Ti)2•







亮度分档

:

代码	最小值	最大值	单位	测试条件
G8	5000	5500	mcd	IF=150mA
G9	5500	6000		
O1	6000	7000		
O2	7000	8000		

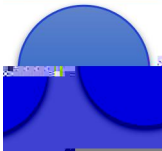
电压分档

:

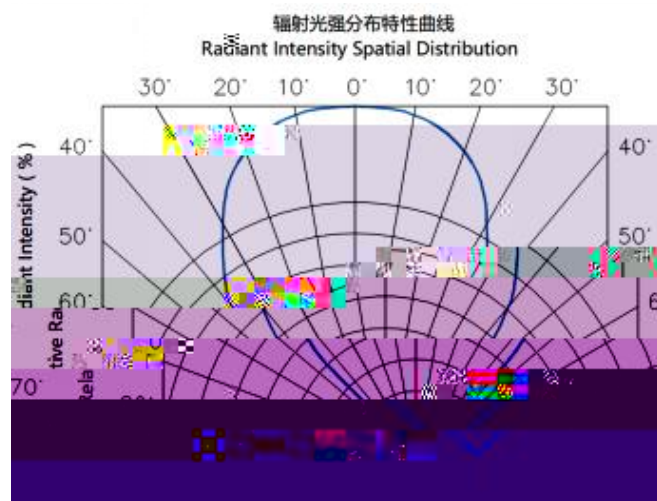
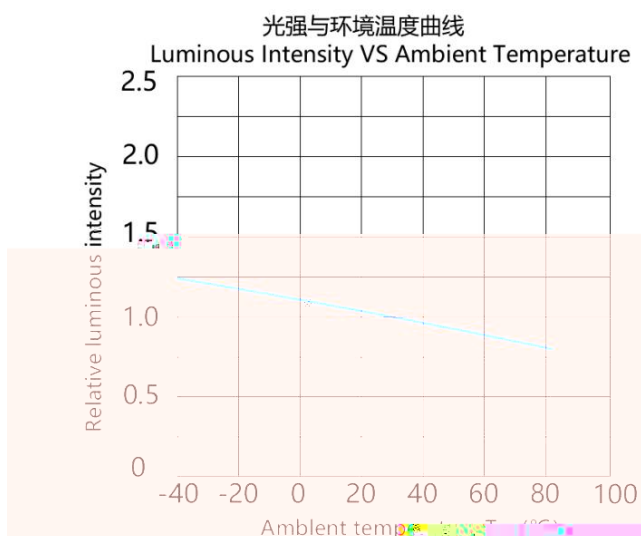
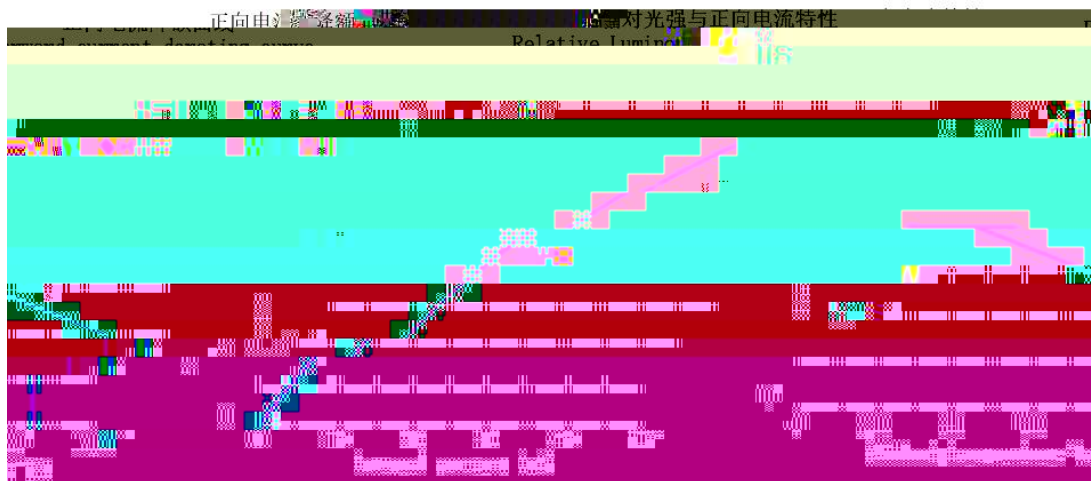
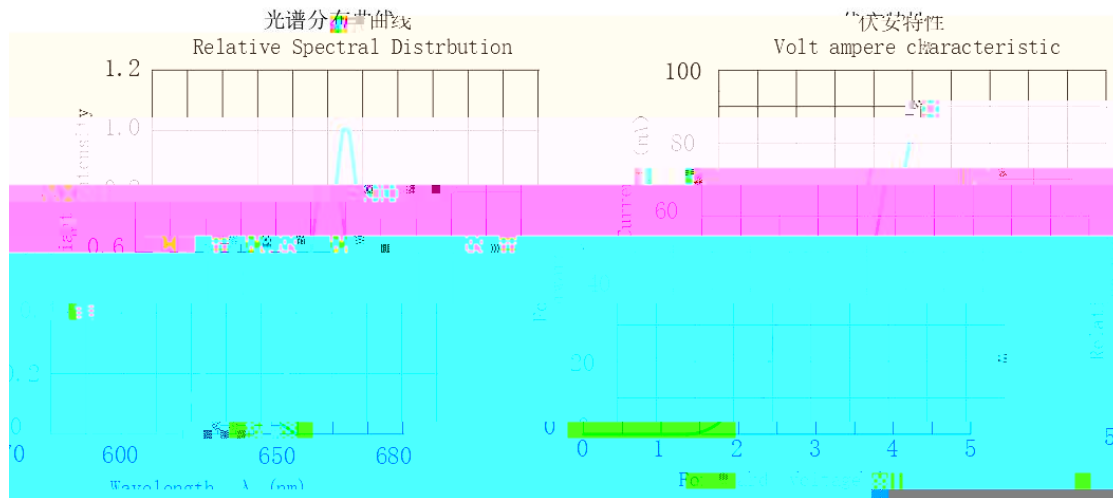
代码	最小值	最大值	单位	测试条件
N12-7	1.8	2.0	V	IF=150mA
N12-8	2.0	2.2		
N12-9	2.2	2.4		

波长分档

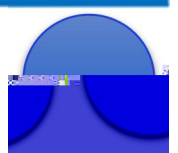
代码	最小值	最大值	单位	测试条件
HR01	615	620	nm	IF=150mA
HR02	620	625		
HR03	625	630		
HR04	630	635		



典型特性曲线



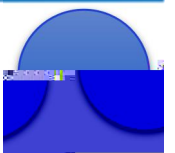
25.5 /Note If not otherwise indicated the test environment temperature is 25.5



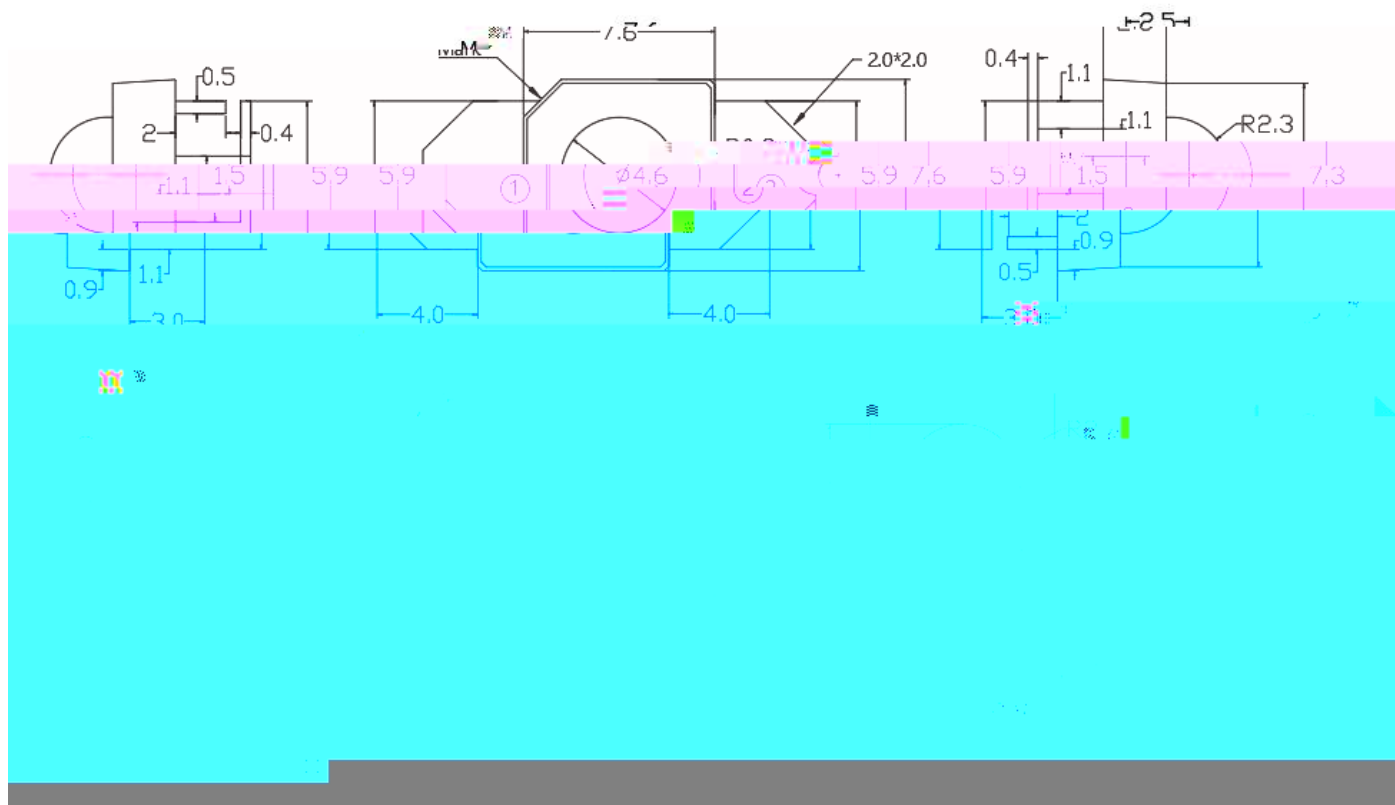
可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Failqty
Endurance test	Working life	Ta=25 ± 5 , IF=20mA	1000hrs	22 PCS	0/1
	High temperature and high humidity experiment	Ta= 85 ± 5 , RH= 85 ~ 90%	1000hrs	22 PCS	0/1
	High-temperature storage	Ta= 85 ± 5	1000hrs	22 PCS	0/1
	Low temperature storage	Ta= -40 ± 5	1000hrs	22 PCS	0/1
Environmental testing	Cold and hot cycle	100 ± 5 -40 ± 5 30mins 5mins 30mins	100 Circles	22 PCS	0/1
	Hot and cold impact	105 ± 5 -45 ± 5 5mins 5mins	100 Circles	22 PCS	0/1
Mechanical Test	Resistance to Soldering Heat	T.sol= 250 ± 5	2times	22 PCS	0/1
	Lead Integrity	Load 2.5N(0.25kgf) 0 ° ~ 90 ° ~ 0 °	3times	22 PCS	0/1



外形尺寸



(Note)

1.

Dimensions are in millimeters.

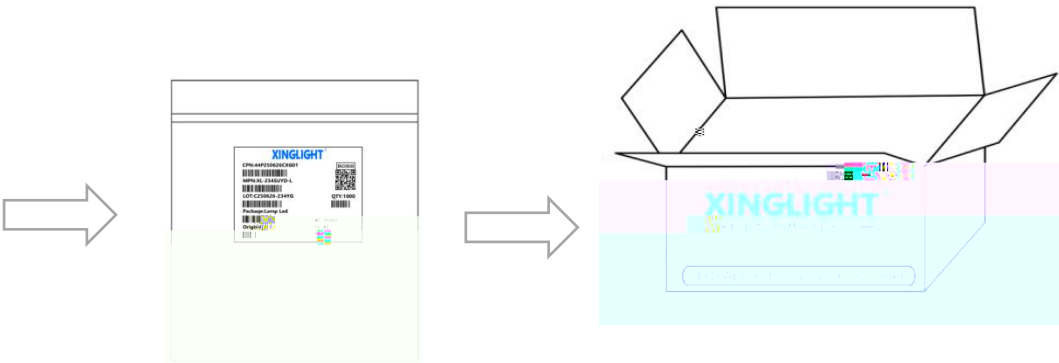
2.

 $\pm 0.50\text{mm}$ Tolerances unless mentioned are $\pm 0.50\text{mm}$.

包装

*
In Bags

*
Moisture Proof and Anti-Static Foil Bag



标签说明 Label Expansion

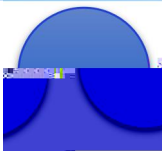
CPN: 批号/档位 LOT: 日期/封装颜色

MPN: 型号 VE: 电压代码

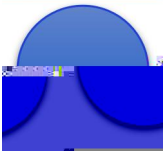
零件号: 150-088 零件号: 150-088

150-088-088 150-088-088

150-088-088



使用注意書)



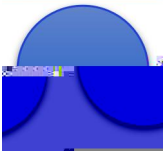
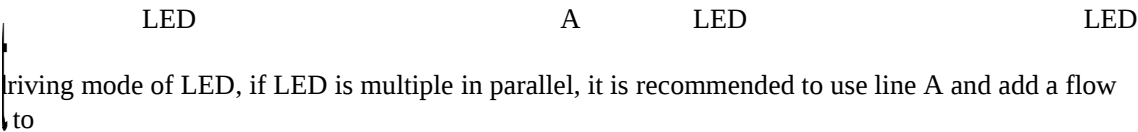
使用注意事项 ()



2mm
LED

LED

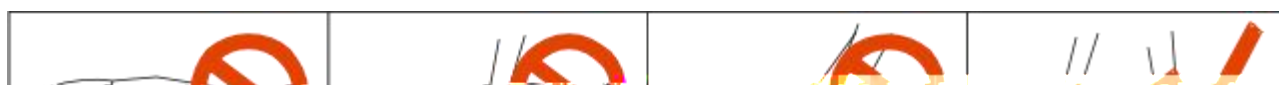
Welding must be conducted below 2mm of colloid bottom. When welding, try to avoid soaking LED
soldering, avoid adding external force on the pin or shaking LED colloid.



8、其他事项:

*

*When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



*LED

